

LINEAR TECHNOLOGY MATERIALS DECLARATION

1t1460bis8-5#pbf

(Engineering Calculation)

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TOTAL MASS (g) : 0.072525

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.001361 | 1000000 | 18765.9804688 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000057 | 1000000 | 785.9375 | | |
| Lead Frame | A42 | Copper (Cu) | 7440-50-8 | 0.000000 | 0 | 0 | | |
| | | Iron (Fe) | 7439-89-6 | 0.014071 | 580000 | 194016.25 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000000 | 0 | 0 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000000 | 0 | 0 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.010189 | 420000 | 140489.765625 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.024260 | 1000000 | 334506 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.001477 | 1000000 | 20363.3925781 | | |
| | | External Plating Total: | | | | 0.001477 | 1000000 | 20363.3925781 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000194 | 1000000 | 2674.94482422 | | |
| Internal Plating Total: | | | | 0.000194 | 1000000 | 2674.94482422 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000540 | 750000 | 7445.72314453 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000180 | 250000 | 2481.90795898 | | |
| Die Attach Total: | | | | 0.000720 | 1000000 | 9927.63183594 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.006641 | 150000 | 91568.609375 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.036302 | 820000 | 500545.6875 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.001107 | 25000 | 15263.7333984 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000221 | 5000 | 3047.23120117 | | |
| | | Encapsulation Total: | | | | 0.044271 | 1000000 | 610425.25 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000185 | 1000000 | 2550.84960938 | | |
| | | | | | TOTAL MASS (g) : | 0.072525 | | |